Preferred Device

Common Anode Silicon Dual Switching Diodes

These Common Anode Silicon Epitaxial Planar Dual Diodes are designed for use in ultra high speed switching applications. The DAP222 device is housed in the SC-75/SOT-416 package which is designed for low power surface mount applications, where board space is at a premium. The DAP202U device is housed in the SC-70/SOT-323 package.

Features

- Fast t_{rr}
- Low C_D
- Available in 8 mm Tape and Reel
- Pb-Free Package is Available

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Value	Unit
Reverse Voltage	V_R	80	Vdc
Peak Reverse Voltage	V_{RM}	80	Vdc
Forward Current	lF	100	mAdc
Peak Forward Current	I _{FM}	300	mAdc
Peak Forward Surge Current	I _{FSM} (1)	2.0	Adc

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

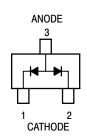
THERMAL CHARACTERISTICS

Rating	Symbol	Max	Unit
Power Dissipation	P_{D}	150	mW
Junction Temperature	TJ	150	°C
Storage Temperature	T _{stg}	-55 ~ + 150	°C



ON Semiconductor®

http://onsemi.com



MARKING DIAGRAMS



SC-75 CASE 463 STYLE 3





SC-70 CASE 419



ORDERING INFORMATION

Device	Package	Shipping [†]
DAP222	SC-75	3000/Tape & Reel
DAP202U	SC-70	3000/Tape & Reel
DAP222T1	SC-75	3000/Tape & Reel
DAP222T1G	SC-75 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

Characteristic	Symbol	Condition	Min	Max	Unit
Reverse Voltage Leakage Current	I _R	V _R = 70 V	_	0.1	μAdc
Forward Voltage	V _F	$I_F = 100 \text{ mA}$	_	1.2	Vdc
Reverse Breakdown Voltage	V_R	I _R = 100 μA	80	_	Vdc
Diode Capacitance	C_D	$V_R = 6.0 \text{ V}, f = 1.0 \text{ MHz}$	_	3.5	pF
Reverse Recovery Time DAP222 DAP202U	t _{rr} (2) t _{tt} (3)	$\begin{aligned} I_F &= 5.0 \text{ mA, } V_R = 6.0 \text{ V, } R_L = 100 \Omega, I_{rr} = 0.1 I_R \\ I_F &= 5.0 \text{ mA, } V_R = 6.0 \text{ V, } R_L = 50 \Omega, I_{rr} = 0.1 I_R \end{aligned}$		4.0 10.0	ns

- t = 1 μS
 t_{rr} Test Circuit for DAP222 in Figure 4.
 trr Test Circuit for DAP202U in Figure 5.

TYPICAL ELECTRICAL CHARACTERISTICS

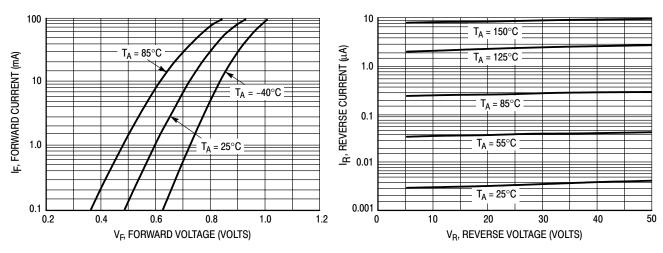


Figure 1. Forward Voltage

Figure 2. Reverse Current

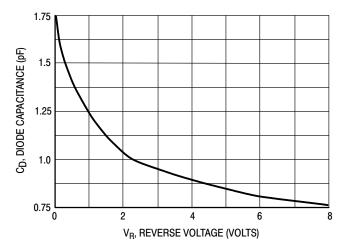


Figure 3. Diode Capacitance

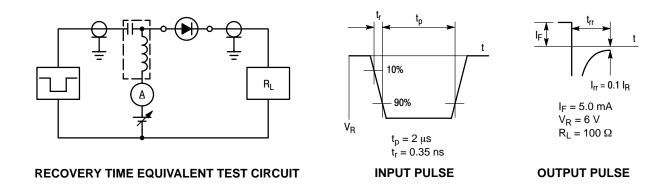


Figure 4. Reverse Recovery Time Test Circuit for the DAP222

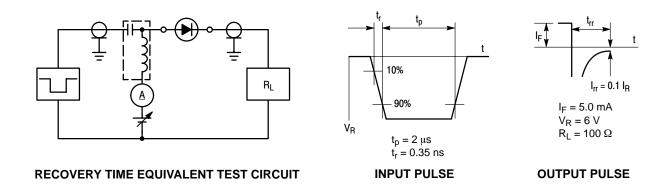
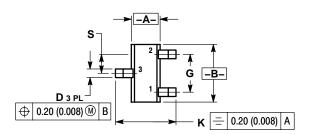
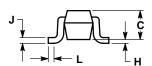


Figure 5. Reverse Recovery Time Test Circuit for the DAP202U

PACKAGE DIMENSIONS

SC-75 (SOT-416) CASE 463-01 ISSUE C





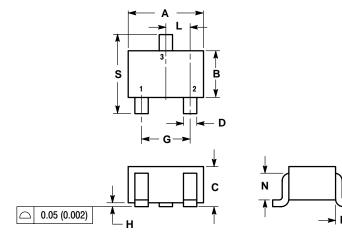
- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	0.70	0.90	0.028	0.035
В	1.40	1.80	0.055	0.071
С	0.60	0.90	0.024	0.035
D	0.15	0.30	0.006	0.012
G	1.00 BSC		0.039 BSC	
Н		0.10		0.004
J	0.10	0.25	0.004	0.010
K	1.45	1.75	0.057	0.069
L	0.10	0.20	0.004	0.008
S	0.50 BSC		0.020	BSC

STYLE 3: PIN 1. ANODE 2. ANODE 3. CATHODE

PACKAGE DIMENSIONS

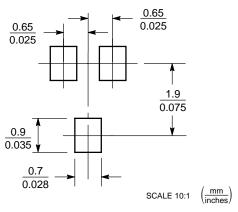
SC-70 (SOT-323) CASE 419-04 **ISSUE L**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
O	0.032	0.040	0.80	1.00
D	0.012	0.016	0.30	0.40
G	0.047	0.055	1.20	1.40
H	0.000	0.004	0.00	0.10
_	0.004	0.010	0.10	0.25
K	0.017 REF		0.425	REF
L	0.026 BSC		0.650	BSC
N	0.028 REF		0.700	REF
S	0.079	0.095	2.00	2.40

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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